

**AMENDMENTS TO THE SPECIFICATION**

Please amend paragraph [0021] as follows:

Next, as seen in Figure 4, the sacrificial layer 201 and the ~~dust particles~~particulates 301 are removed, such as by a wet step. For example, in the case of a phenyl resin, the sacrificial layer 201 can be removed using a wet chemical process. Alternatively, various types of etching may be utilized. In one embodiment, the removal of the sacrificial layer 201 should be tailored to the removal of the material constituting the sacrificial layer 201, with little or no damage to the IC package and other components. Various techniques are known in the art for performing this removal, including but not limited to a wet chemical process.